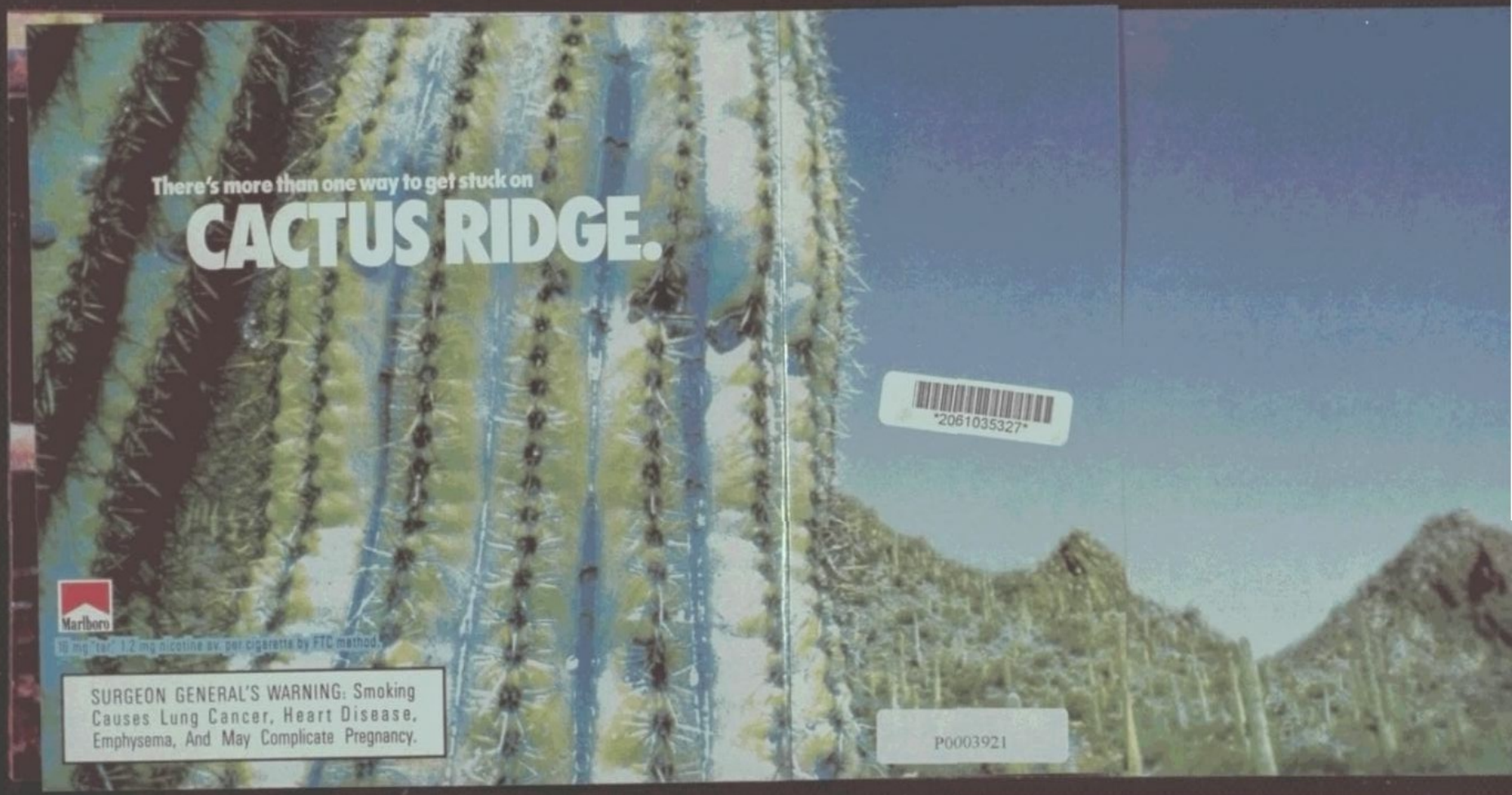


Source: https://www.industrydocuments.ucsf.edu/docs/2061035327